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PATENTS ABSTRACTS OF JAPAN

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(54) DEVICE FOR MOUNTING CHIP

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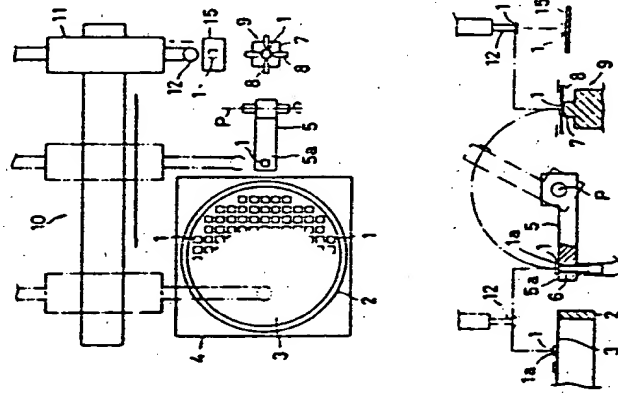
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PURPOSE: To eliminate manual labor in reversing a semiconductor chip and to largely improve working efficiency by reversing the chip upside down by a reversely feeding arm, disposing a bump in a downward attitude, and then placing it on a positioning unit.

CONSTITUTION: A flip-chip 1 disposed on an expanding sheet 10 in an upward attitude of a bump 1a is first fed by a chip feeder 10, and placed on the movable end of a reversely feeding arm 5. The chip 1 attracted to and held at the movable end is placed on a positioning unit 9 by the reversing operation of the arm 5. In this case, the chip 1 is disposed in a downward attitude at its bump 1a. The chip 1 placed on the unit 9 to be positioned is attracted to and held at the feeder 10, fed to a predetermined position on a semiconductor substrate 15, and placed in the downward attitude of the bump 1a. Thus, its working efficiency can be largely improved.



LEGENDE

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(54) Titel der Patentanmeldung

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